

Plastic-Encapsulate Diodes GS1Z

Features

- ◇ For surface mounted application
- ♦ Esay pick and place
- \diamond Low forward voltage drop
- ♦ High current capability
- ♦ High surge current capability
- High temperature soldering guaranteed: 260°C / 10 seconds at terminals
- Plastic material used carriers Underwriters Laboratory Classification 94V-0



Dimensions in inches and (millimeters) $DO\mbox{-}214AC\ (SMA)$

Mechanical Data

- Case:JEDEC DO-214AC,molded plastic body over passivated chip
- ◊ Polarity: Color band denotes cathode end

Average Forward current	I _{F(AV)}	1.0A	T _L = 110°C
Peak Forward Surge Current	I _{FSM}	30A	8.3ms, half sine,
Maximum Instantaneous Forward Voltage	V_{F}	1.15V	I _{FM} = 1.0A; T _J = 25°C*
Maximum DC Reverse Current At Rated DC Blocking Voltage	I _R	1μΑ 50μΑ	T _J = 25°C T _J = 100°C
Typical Reverse Recovery Time	T _{rr}	2500ns	I _F =0.5A, I _R =1.0A, I _{rr} =0.25A

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

*Pulse test: Pulse width 300 $\mu sec,$ Duty cycle 2%

Note 1: High Temperature Solder Exemptions Applied, see EU Directive Annex 7a.



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Typical Characteristics



Instantaneous Reverse Current - uA Percent Of Rated Peak Reverse Voltage - Volts



Average Forward Rectified Current - A Lead Temperature -°C



Peak Forward Surge Current - A Number Of Cycles At 60Hz - Cycles

